

June 28 - July 1, 2020

Hilton Deansgate
Manchester, UK



CALL FOR PAPERS

IMPORTANT DATES

January 27, 2020

- Tutorial Proposal Submission Deadline
- Focused Session Proposal Submission Deadline

February 3, 2020

- Tutorial Proposal Notification Acceptance
- Focused Session Notification Acceptance

March 1, 2020

Full Paper Submission Deadline

April 20, 2020

Notification of Acceptance

May 1, 2020

Final Manuscript Submission Deadline

May 8, 2020

Standard Registration Deadline

The 2nd IEEE International Conference on Flexible and Printable Sensors and Systems (FLEPS 2020) will be held in Manchester, United Kingdom.

IEEE FLEPS 2020 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic Electronics
- » Emerging Materials for Flexible and Printable Systems
- » Manufacturing Techniques
- » High-throughput Printable Electronics
- » Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- » Stretchable/Shrinkable Sensors and Electronics
- » Soft/Smart Wearable and Implantable Sensing Systems
- » Disposable/Reusable Sensors and Electronics
- » Printed Large-Area Sensors and Systems
- » Flexible or Printed Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » Emerging applications of Flexible Electronics inc. IoT, smart cities etc.
- » Simulation and Modelling
- » Flexible/Printable Electronics in context with Circular Economy and green electronics

PUBLICATION OF PAPERS

Presented papers will be included in the Proceedings of IEEE FLEPS 2020 and in IEEE Xplore pending author requirements being met. Authors may submit an extended IEEE FLEPS 2020 papers to the Special Journal Issue in the IEEE Sensors Journal.

EXHIBITION & PATRON OPPORTUNITIES

The Conference exhibit area will provide your company or organization with the opportunity to inform and display your latest products, services, equipment, books, journals, and publications to attendees from around the world.

For further information, contact:

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Please visit: 2020.ieee-fleps.org



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